ASBOCIATION CONNECTING LECTRONICS INDUSTRIES	C. Bannockb	ourn. Illinois. A	Ill rights reserved untions.	Inder both This docu level part	ment is a of the second	declaratio aration en	n of the substa	nces w lower l	vithin the manufacture level materials for wh	er listed it hich the m	tem. Note: it nanufacturer	the item is an as has engineering	ssembly with lower responsibility.
	IPC Web Site for Information on IPC-1752 Standard Forr http://www.ipc.org/IPC-175x Dist								ials and Mfg Information				
Supplier Information													
Company name*	Company unique ID			Unique	Unique ID Authority					Response Date*			
onsemi										2025-05-13			
Contact Name Ti			Title - Contact			Phone - Contact*				Email - Contact*			
Product-Env-Stewards Pro			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Authorized Representative* Ti			Title - Representative			Phone - Representative*			Email - Representative*				
Product-Env-Stewards	Product Enviro Compliance			NA	NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Item	n Number Mfr Item Name			Effecti	ve Date	Version	Ma	anufacturing Site		Weight*	UOM	Unit Type
	NCP1090	NCP1096PAG Integrated PoE integrated hot		D Interface Controller wit ap FET, IEEE 802.3bt, 90	with 2025-05-13 90W			BE	BE4		64.0	mg	Each
Manufacturing Proccess Information	ion												
Terminal Plating / Grid Array Ma	Terminal Plating / Grid Array Material Terminal Base A		Alloy J-STD-020 MSL Rating		Pe	Peak Process Body Temperature Max Time at Peak		Max Time at Peak	Temperature Number of Reflow Cycles				
Matte Tin (Sn) - annealed CU		U Alloy 2		26	260 C 30		30	seconds 3					
Comments													
ATTENTION: MSL 2 Rated item require	s Dry Pack (a	fter electrical	test)										
For more information regarding material	composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	5.3	mg	Supplier	Silicon (Si)	7440-21-3		5.3	mg
Die Attach	1.3	mg	Supplier	Silver (Ag)	7440-22-4		1.105	mg
			Supplier	Acrylic resins	Proprietary Data		0.195	mg
Die Attach Tape	1.3	mg	Supplier	Oxirane, (chloromethyl)-, homopolymer	24969-06-0		0.195	mg
			Supplier	2-Propenoic acid, 2-methyl-, polymer with butyl 2-propenoate and methyl 2- methyl-2-propenoate	25035-69-2		0.195	mg
			Supplier	Proprietary	Proprietary Data		0.13	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.585	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.195	mg
Lead Frame	32.6	mg	Supplier	Silver (Ag)	7440-22-4		0.0978	mg
			Supplier	Magnesium (Mg)	7439-95-4		0.0326	mg
			Supplier	Silicon (Si)	7440-21-3		0.2282	mg
			В	Nickel (Ni)	7440-02-0		0.978	mg
			Supplier	Copper (Cu)	7440-50-8		31.2634	mg
Mold Compound-Black	22.9	mg		Epoxy resin	proprietary data		1.603	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0687	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		20.839	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.3893	mg
Plating	0.5	mg	Supplier	Tin (Sn)	7440-31-5		0.5	mg
Wire Bond - Au	0.1	mg	Supplier	Gold (Au)	7440-57-5		0.1	mg